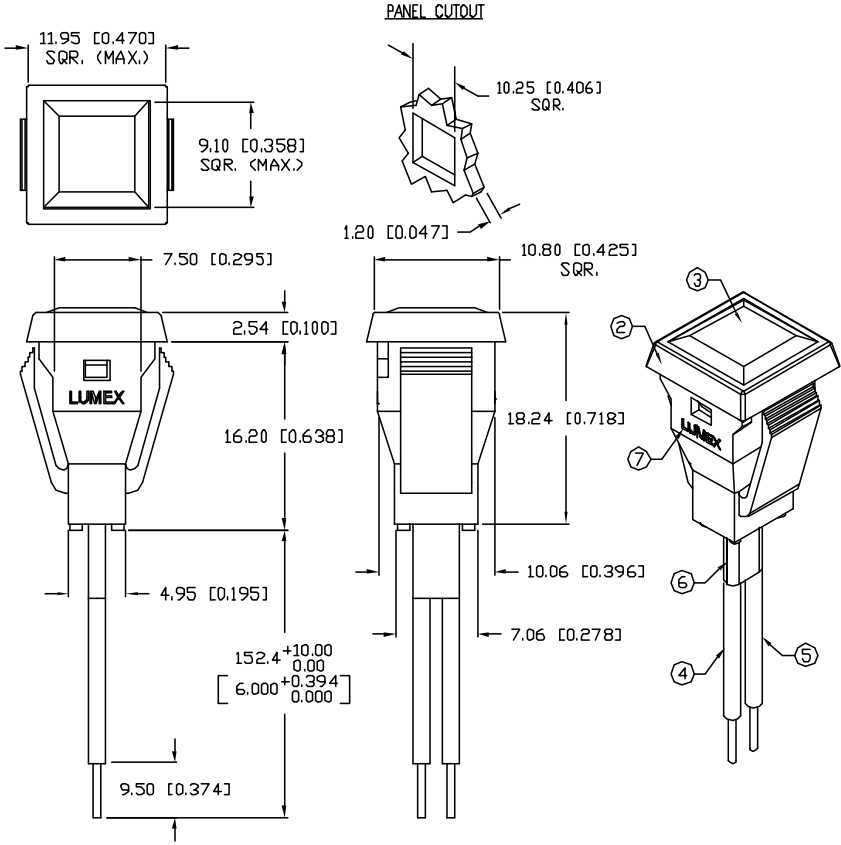


UNCONTROLLED DOCUMENT

PART NUMBER  
SSI-LXMP5011GC1215

REV.



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $V_f=12\text{V}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		12.0	14.0	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		8		mcd	$V_f=12\text{V}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	WATER CLEAR LENS				

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD VOLTAGE	14	V
STEADY CURRENT	12	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

- NOTES:
- SSL-LX4073GD-12V LED, GREEN. (INSIDE)
  - SSH-LXMP5011 HOLDER, BLACK.
  - LXP-LXN5011C, WATER CLEAR LENS.
  - ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, TOP OVERCOAT, RED INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.
  - CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, TOP OVERCOAT, BLACK INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.
  - HEAT SHRINK: LXP-HEATSHRINK-4, 1/8" x 1/2". (1 PIECE)
  - 'LUMEX' ON FRONT (ANODE SIDE) OF PART.

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\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION -0.00, MAX.=+0.00 -DECIMAL PRECISION

REV. PART NUMBER  
SSI-LXMP5011GC1215

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290 E. HELEN ROAD  
PALATINE, IL 60067-6976  
PHONE: +1.847.359.2790  
US WEB: www.lumex.com  
TW WEB: www.lumex.com.tw

12mm SQUARE PANEL INDICATOR WITH LENS.  
565nm GREEN LED, 12V,  
WATER CLEAR LENS, 6" WIRE LEADS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JO  
CHECKED BY:  
APPROVED BY:  
DATE: 7.16.04  
PAGE: 1 OF 1  
SCALE: N/A